

TSMC97-306

Reissue Application no. 10/062,314

Reissue Application Patent no. 6,019,906



May 9, 2002

TO: Commissioner of Patents and Trademarks
Washington, D.C. 20231

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SUBJECT: Reissue Application of:

Patent #: 6,019,906

Issue Date: Feb. 1, 2000

Inventor: Syun-Ming Jang, Ming-Hsin Huang

Title: Hard Masking Method for Forming Patterned Oxygen
Containing Plasma Etchable Layer

Reissue Serial Number: **10/062,314**

Reissue File Date: **Feb. 1, 2002**

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TC 1760

PRELIMINARY AMENDMENT

This regards the Reissue Application of the above identified patent. Please amend
the above-identified patent as follows:

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States
Postal Service as first class mail in an envelope addressed to: Commissioner of
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Date: 5/9/02